

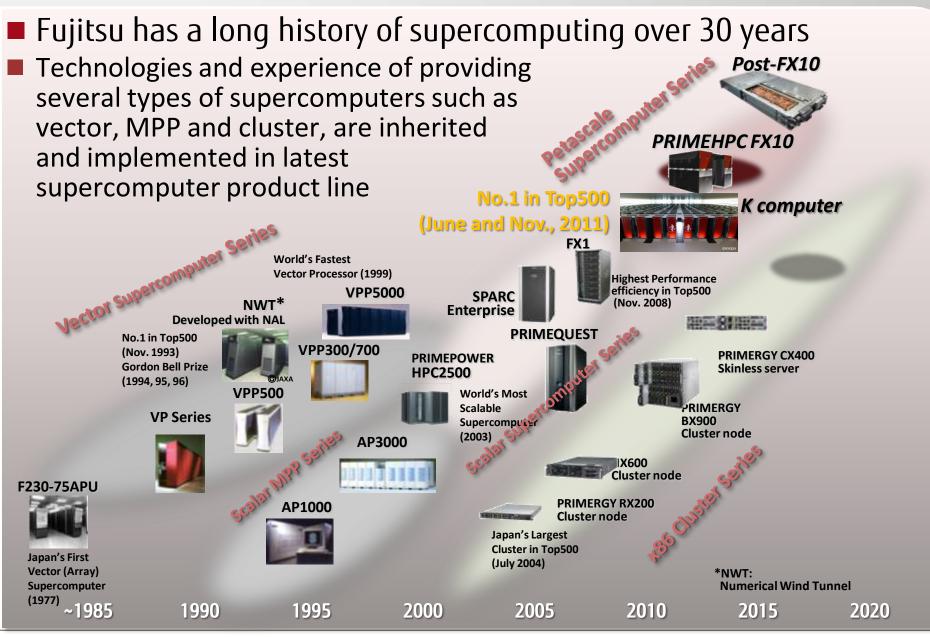
Introduction of Fujitsu's next-generation supercomputer

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July 16, 2014

HPC Platform Solutions





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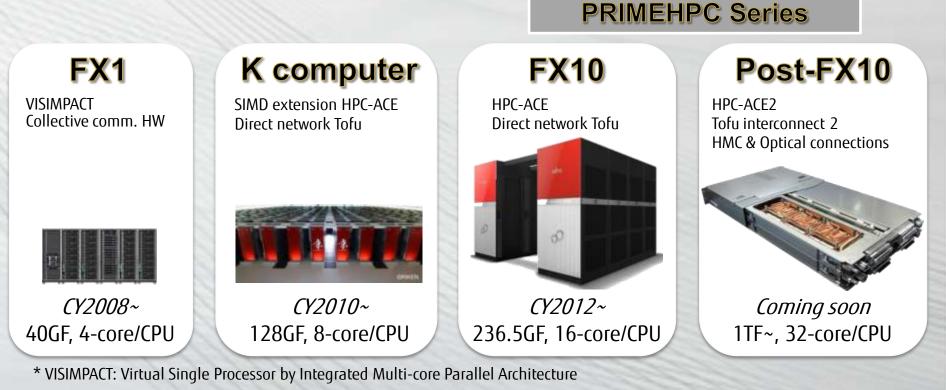
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K computer and Fujitsu PRIMEHPC series

FUJITSU

Single CPU/node architecture for multicore

- Good Bytes/flop and scalability
- Key technologies for massively parallel supercomputers
 - Original CPU and interconnect
 - Support for tens of millions of cores (VISIMPACT*, Collective comm. HW)



Architecture continuity for compatibility

- Upper compatible CPU:
 - Binary-compatible with the K computer & PRIMEHPC FX10
 - Good byte/flop balance
- New features:
 - New instructions (stride load/store, indirect load/store, permutation, concatenation)
 - Improved micro architecture (out-of-order, branch-prediction, etc.)
- For distributed parallel executions:
 - Compatible interconnect architecture
 - Improved interconnect bandwidth







The K computer and the evolution of PRIMEHPC



	K computer	PRIMEHPC FX10	Post-FX10
CPU	SPARC64 VIIIfx	SPARC64 IXfx	SPARC64 XIfx
Peak perf.	128 GFLOPS	236.5 GFLOPS	1TFLOPS ~
# of cores	8	16	32 + 2
Метогу	DDR3 SDRAM	←	НМС
Interconnect	Tofu Interconnect	\leftarrow	Tofu Interconnect 2
System size	11PFLOPS	Max. 23PFLOPS	Max. 100PFLOPS
Link BW	5GB/s x bidirectional	\leftarrow	12.5GB/s x bidirectional

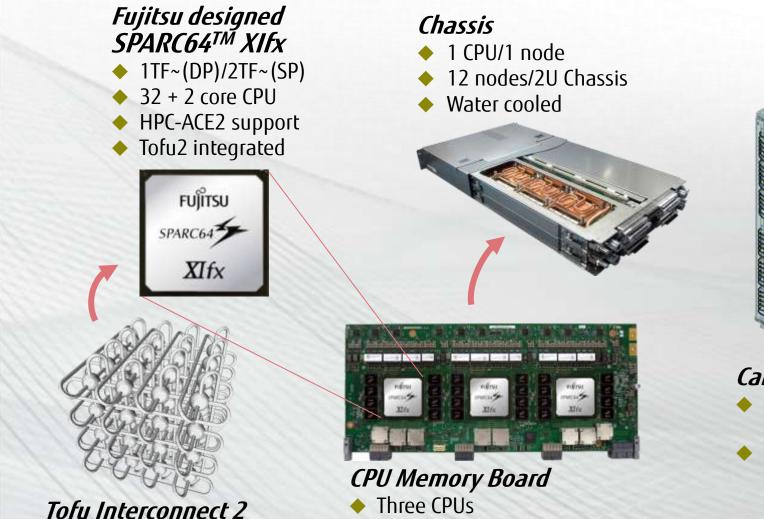






Feature and Configuration of Post-FX10





12.5 GB/s×2(in/out)/link

10 links/node

Optical technology

- Cabinet
- 200~ nodes/cabinet High-density
- 100% water cooled with EXCU (option)

3 x 8 Micron's HMCs

8 Finisar's opt modules, BOA, for

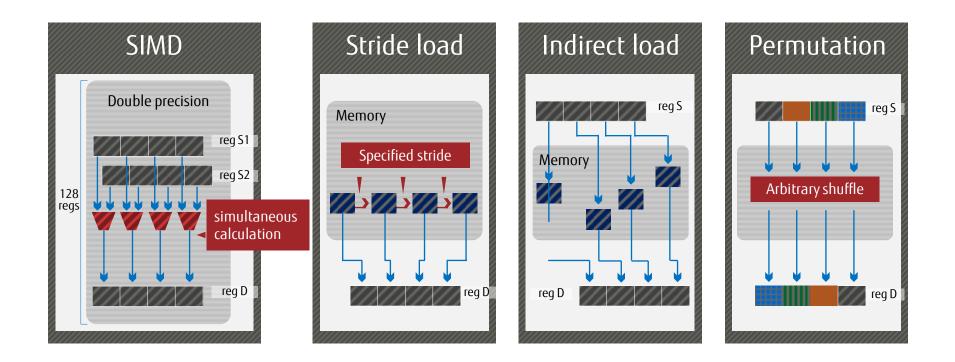
inter-chassis connections

Flexible SIMD operations

FUjitsu

New 256bit wide SIMD functions enable versatile operations
Four double-precision calculations

Stride load/store, Indirect (list) load/store, Permutation, Concatenation



Tofu Interconnect 2

Successor to Tofu Interconnect

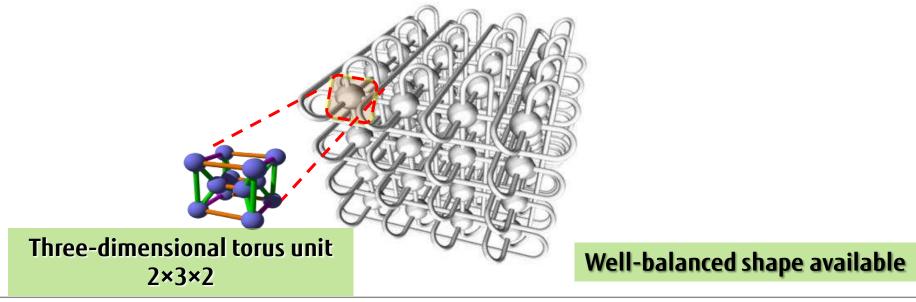
 Highly scalable, 6-dimensional mesh/torus topology
 Increased link bandwidth by 2.5 times to 12.5 GB/s

Interconnect integrated into CPU

 System-on-chip (SoC) removes off-chip I/O
 Improved packaging density and energy efficiency

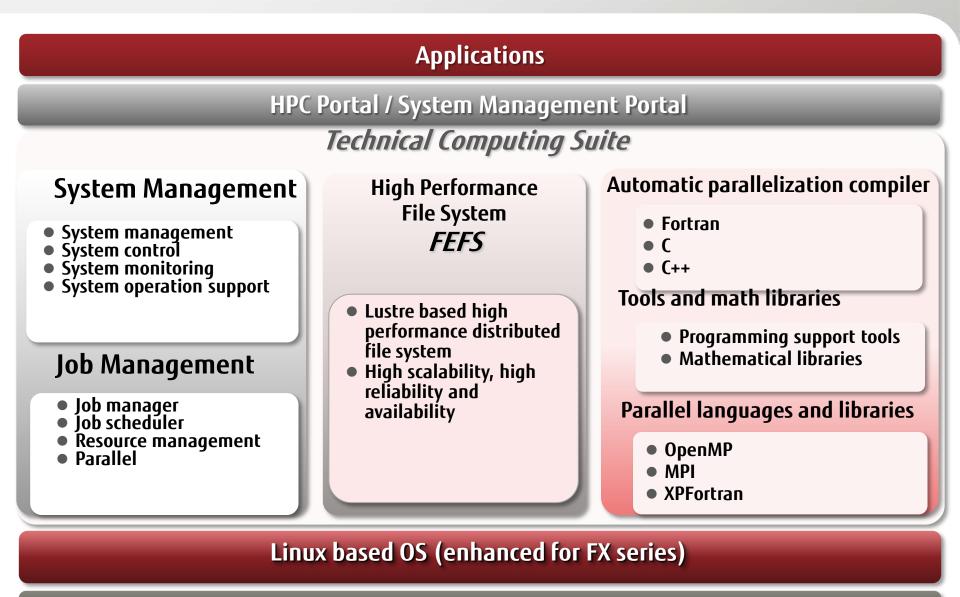
Optical cable connection between chassis

Scalable three-dimensional torus



Entire software stack is enhanced for Post-FX10



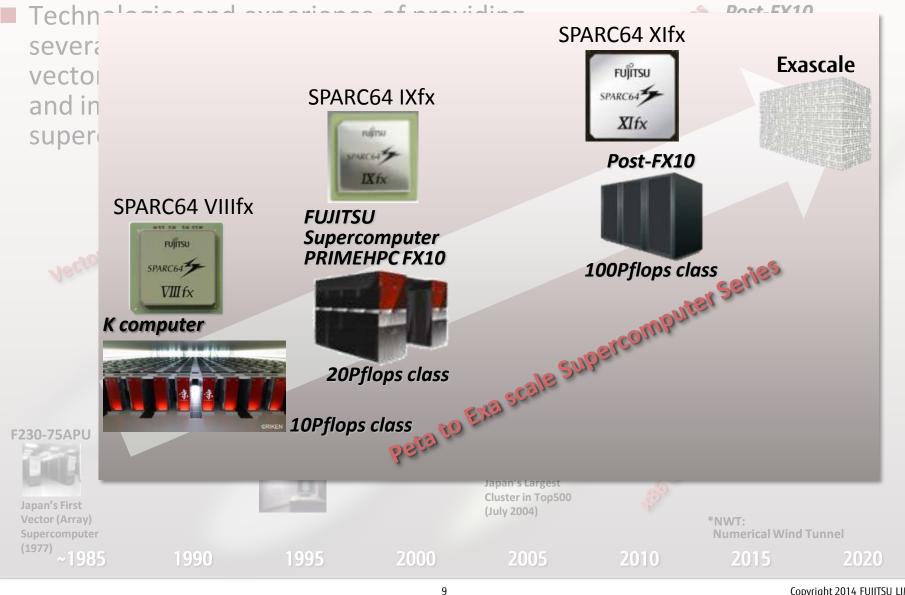


PRIMEHPC FX series

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